Application No.: 10/802,549   2   Docket No.: 524322000600

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

In the claims:

Claim 1 (Original): A method of adjusting a die placement of dice to be formed on a wafer, the method comprising:

    a) obtaining a die placement of dice to be formed on the wafer;

    b) obtaining one or more locations on the wafer contacted by one or more processing structures or a substance emitted by one or more processing structures; and

    c) adjusting the die placement based on the obtained one or more locations on the wafer.

Claim 2 (Original): The method of claim 1, wherein the die placement is adjusted to increase yield of the dice formed on the wafer.

Claim 3 (Original): The method of claim 2, wherein step c) of claim 1 comprises:

    generating a plurality of die placements having different arrangements of dice;

    determining a yield associated with each of the plurality of die placements; and

    selecting a die placement with the highest yield from the plurality of die placements.

Claim 4 (Original): The method of claim 3, wherein yield is determined based on the number of good dice formed on the wafer.

Claim 5 (Previously Presented): The method of claim 1, further comprising:

    d) adjusting the one or more locations on the wafer based on the die placement, wherein the die placement and the one or more locations on the wafer are adjusted together.

Claim 6 (Original): The method of claim 5, wherein the die placement and one or more locations on the wafer are adjusted to increase yield of the dice formed on the wafer.

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Claim 7 (Original): The method of claim 6, wherein step c) of claim 1 and step d) of claim 5 comprise:

      generating a plurality of combinations of die placement and one or more locations on the wafer;

      determining a yield associated with each of the plurality of combinations of die placement and one or more locations on the wafer; and

      selecting a combination of die placement and one or more locations on the wafer with the highest yield from the plurality of combinations of die placement and one or more locations on the wafer.

Claim 8 (Original): The method of claim 1, wherein the die placement includes an arrangement of reticle arrays, and wherein each reticle array includes an arrangement of dice.

Claim 9 (Original): The method of claim 1, wherein the one or more processing structures include a clamp to hold the wafer during a fabrication process.

Claim 10 (Original): The method of claim 1, wherein the one or more processing structures include a jet that emits a chemical solution or water at the wafer.

Claim 11 (Original): The method of claim 1, wherein the dice are formed on a first surface on the wafer, and wherein the one or more locations are on the first surface of the wafer or on a second surface on the wafer opposite the first surface.

Claim 12 (Original): A method of adjusting a die placement of dice to be formed on a wafer, the method comprising:

      a) obtaining a die placement of dice to be formed on the wafer, the die placement having an arrangement of reticle arrays, wherein each reticle array includes an arrangement of dice to be formed on the wafer;

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b) obtaining one or more locations on the wafer contacted by one or more clamps; and

c) adjusting the die placement based on the obtained one or more locations on the wafer.

Claim 13 (Original): The method of claim 12, wherein step c) of claim 12 comprises:

generating different die placements having different arrangements of reticle arrays;

determining yields associated with the different die placements; and

selecting a die placement with the highest yield from the different die placements.

Claim 14 (Previously Presented): The method of claim 12, further comprising:

d) adjusting the one or more locations on the wafer based on the die placement, wherein the die placement and the one or more locations on the wafer are adjusted together.

Claim 15 (Original): The method of claim 14, wherein step c) of claim 12 and step d) of claim 14 comprise:

generating a plurality of combinations of die placement and one or more locations on the wafer;

determining a yield associated with each of the plurality of combinations of die placement and one or more locations on the wafer; and

selecting a combination of die placement and one or more locations on the wafer with the highest yield from the plurality of combinations of die placement and one or more locations on the wafer.

Claims 16-20 (Canceled).

Claim 21 (Previously Presented): A method of adjusting a die placement of dice to be formed on a wafer, the method comprising:

a) obtaining a die placement of dice to be formed on the wafer;

b) obtaining one or more locations on the wafer contacted by one or more processing structures or a substance emitted by one or more processing structures; and

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c) adjusting the die placement based on the obtained one or more locations on the wafer, wherein the adjusted die placement produces a higher yield of dice formed on the wafer than the die placement obtained in step a).

Claim 22 (Previously Presented): The method of claim 21, wherein step c) of claim 21 comprises:

generating a plurality of die placements having different arrangements of dice;

determining a yield associated with each of the plurality of die placements; and

selecting a die placement with the highest yield from the plurality of die placements.

Claim 23 (Previously Presented): The method of claim 21, further comprising:

d) adjusting the one or more locations on the wafer based on the die placement, wherein the die placement and the one or more locations on the wafer are adjusted together.

Claim 24 (Previously Presented): The method of claim 23, wherein step c) of claim 21 and step d) of claim 23 comprise:

generating a plurality of combinations of die placement and one or more locations on the wafer;

determining a yield associated with each of the plurality of combinations of die placement and one or more locations on the wafer; and

selecting a combination of die placement and one or more locations on the wafer with the highest yield from the plurality of combinations of die placement and one or more locations on the wafer.

Claim 25 (Previously Presented): The method of claim 21, wherein the dice are formed on a first surface on the wafer, and wherein the one or more locations are on the first surface of the wafer or on a second surface on the wafer opposite the first surface.

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Claim 26 (New): A computer-readable medium having computer-executable instructions to adjust a die placement of dice to be formed on a wafer, comprising instructions for:

a) obtaining a die placement of dice to be formed on the wafer;

b) obtaining one or more locations on the wafer contacted by one or more processing structures or a substance emitted by one or more processing structures; and

c) adjusting the die placement based on the obtained one or more locations on the wafer, wherein the adjusted die placement produces a higher yield of dice formed on the wafer than the die placement obtained in step a).

Claim 27 (New): The computer-readable medium of claim 26, wherein c) of claim 26, comprises instructions for:

generating a plurality of die placements having different arrangements of dice;

determining a yield associated with each of the plurality of die placements; and

selecting a die placement with the highest yield from the plurality of die placements.

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